



N 沟道增强型场效应晶体管
N-CHANNEL MOSFET
FHP100N8F6A/FHS100N8F6A

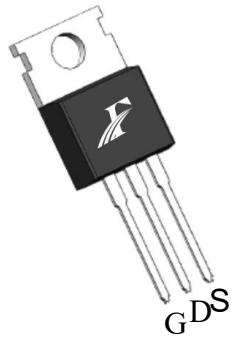
主要参数 MAIN CHARACTERISTICS

ID (Silicon Limited)	120A
VDSS	85 V
Rdson-typ (@Vgs=10V)	5.3 mΩ
Qg-typ	67nC

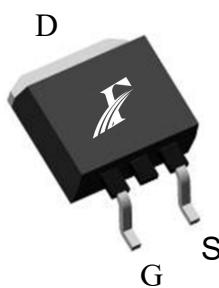
用途 APPLICATIONS

电池管理系统	BMS
电机控制和驱动	Motor control and drive
不间断电源	UPS
开关电源	Switch Mode Power Supplies

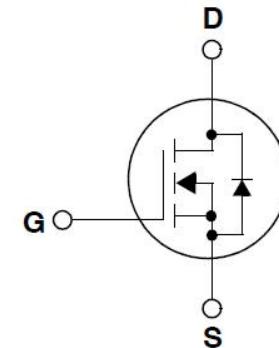
封装形式 Package



TO-220
FHP series



TO-263
FHS series



绝对最大额定值 ABSOLUTE RATINGS (Tc=25°C)

项目 Parameter	符号 Symbol	数值 Value		单位 Unit
		FHP100N8F6A	FHS100N8F6A	
最高漏极—源极直流电压 Drain-Source Voltage	VDS	85		V
连续漏极电流* Drain Current -continuous *	Id (Tc=25°C), Silicon Limited	120		A
	Id (Tc=25°C) , Package Limited	80		
	Id (Tc=125°C), Silicon Limited	56		
最大脉冲漏极电流 (注 1) Drain Current – pulse (note 1)	IdM	320		A
最高栅源电压 Gate-Source Voltage	VGS	±20		V
单脉冲雪崩能量 (注 2) Single Pulsed Avalanche Energy (note 2)	EAS	200		mJ
雪崩电流 (注 1) Avalanche Current (note 1)	IAR	20		A
重复雪崩能量 (注 1) Repetitive Avalanche Current (note 1)	EAR	16		mJ
二极管反向恢复最大电压变化速率 (注 3) Peak Diode Recovery dv/dt (note 3)	dv/dt	5.0		V/ns
耗散功率 Power Dissipation	PD (TC=25°C)	156		W
	-Derate above 25°C	1.25		W/°C
最高结温及存储温度 Operating and Storage Temperature Range	TJ, TSTG	-55~+150		°C
引线最高焊接温度 Maximum Lead Temperature for Soldering Purposes	TL	260		°C

*漏极电流由最高结温限制

*Drain current limited by maximum junction temperature

电特性 ELECTRICAL CHARACTERISTICS

项目 Parameter	符号 Symbol	测试条件 Tests conditions	最小 Min	典型 Typ	最大 Max	单位 Units	
关态特性 Off -Characteristics							
漏—源击穿电压 Drain-Source Voltage	BVDSS	Id=250μA, Vgs=0V	85	95	-	V	
击穿电压温度特性 Breakdown Voltage Temperature Coefficient	ΔBVDSS/Δ TJ	Id=250μA, referenced to 25°C	-	0.08	-	V/°C	
零栅压下漏极漏电流 Zero Gate Voltage Drain Current	Idss	Vds=85V, Vgs=0V, Tc=25°C Vds=68V, Tc=125°C	- -	- -	1 100	μA μA	
栅极体漏电流 Gate-body leakage current	IGSS (F/R)	Vds=0V, Vgs =±20V	-	-	±100	nA	
通态特性 On-Characteristics							
阈值电压 Gate Threshold Voltage	VGS(th)	Vds = Vgs , Id=250μA	2	-	4	V	
静态导通电阻 Static Drain-Source On-Resistance	RDS(ON)	Vgs =10V , Id=50A	-	5.3	6.5	mΩ	
正向跨导 Forward Transconductance	gfs	Vds = 10V, Id=50A (note 4)	-	65	-	S	
动态特性 Dynamic Characteristics							
栅电阻 Gate Resistance	Rg	f=1.0MHz, Vds OPEN	-	1.5	-	Ω	
输入电容 Input capacitance	Ciss	Vds=40V, Vgs =0V, f=1.0MHz	-	3374	-	pF	
输出电容 Output capacitance	Coss		-	507	-		
反向传输电容 Reverse transfer capacitance	Crss		-	18	-		
开关特性 Switching Characteristics							
延迟时间 Turn-On delay time	td(on)	Vdd=40V, Id=50A, Rg=20Ω Vgs =10V (note 4, 5)	-	37	-	ns	
上升时间 Turn-On rise time	tr		-	30	-	ns	
延迟时间 Turn-Off delay time	td(off)		-	37	-	ns	
下降时间 Turn-Off Fall time	tf		-	20	-	ns	
栅极电荷总量 Total Gate Charge	Qg	Vds =40V , Id=50A , Vgs =10V (note 4, 5)	-	67	-	nC	
栅—源电荷 Gate-Source charge	Qgs		-	19	-	nC	
栅—漏电荷 Gate-Drain charge	Qgd		-	37	-	nC	
漏—源二极管特性及最大额定值 Drain-Source Diode Characteristics and Maximum Ratings							
正向最大连续电流 Maximum Continuous Drain -Source Diode Forward Current	Is		-	-	80	A	
正向最大脉冲电流 Maximum Pulsed Drain-Source Diode Forward Current	IsM		-	-	320	A	
正向压降 Drain-Source Diode Forward Voltage	Vsd	Vgs=0V, Is=50A	-	-	1.2	V	
反向恢复时间 Reverse recovery time	trr	Vgs=0V, Is=30A ,dI/dt=100A/μs (note 4)	-	48	-	ns	
反向恢复电荷 Reverse recovery charge	Qrr		-	115	-	nC	

热特性 THERMAL CHARACTERISTIC

项目 Parameter	符号 Symbol	FHP100N8F6A	FHS100N8F6A	单位 Unit
结到管壳的热阻 Thermal Resistance, Junction to Case	R _{th(j-c)}	0.8		°C/W
结到环境的热阻 Thermal Resistance, Junction to Ambient	R _{th(j-A)}	62.5		°C/W

注释:

- 1: 脉冲宽度由最高结温限制
- 2: L=1mH, I_{AS}=20A, V_{DD}=48V, R_G=25 Ω,起始结温 T_J=25°C
- 3: I_{SD} ≤ 80A, di/dt ≤ 300A/μs, V_{DD} ≤ BV_{DSS}, 起始结温 T_J=25°C
- 4: 脉冲测试: 脉冲宽度 ≤ 300μs, 占空比≤2%
- 5: 基本与工作温度无关

Notes:

- 1: Pulse width limited by maximum junction temperature
- 2: L=1mH, I_{AS}=20A, V_{DD}=48V, R_G=25 Ω, Starting T_J=25°C
- 3: I_{SD} ≤ 80A, di/dt ≤ 300A/μs, V_{DD} ≤ BV_{DSS}, Starting T_J=25°C
- 4: Pulse Test: Pulse Width ≤ 300μs, Duty Cycle≤2%
- 5: Essentially independent of operating temperature

Typical Performance

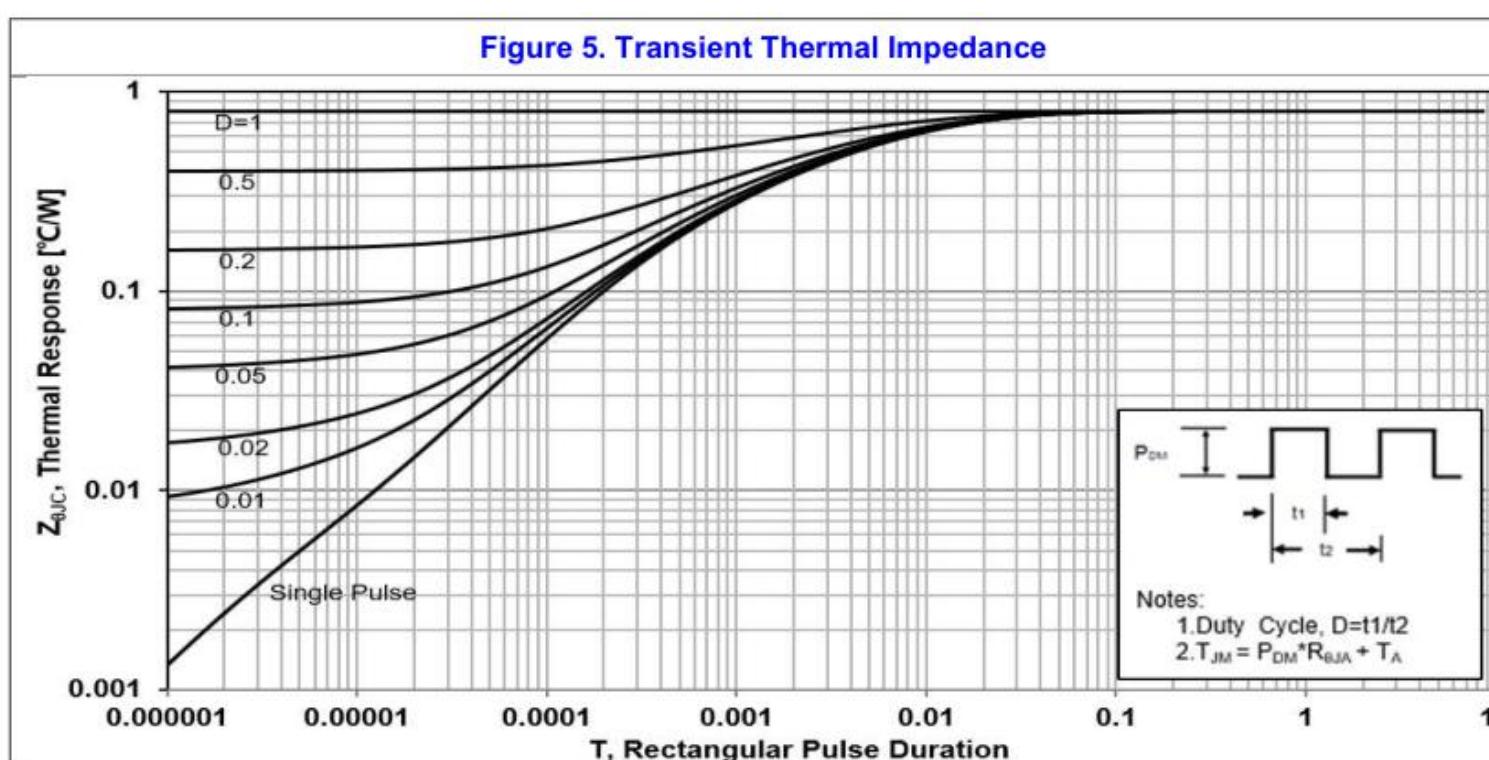
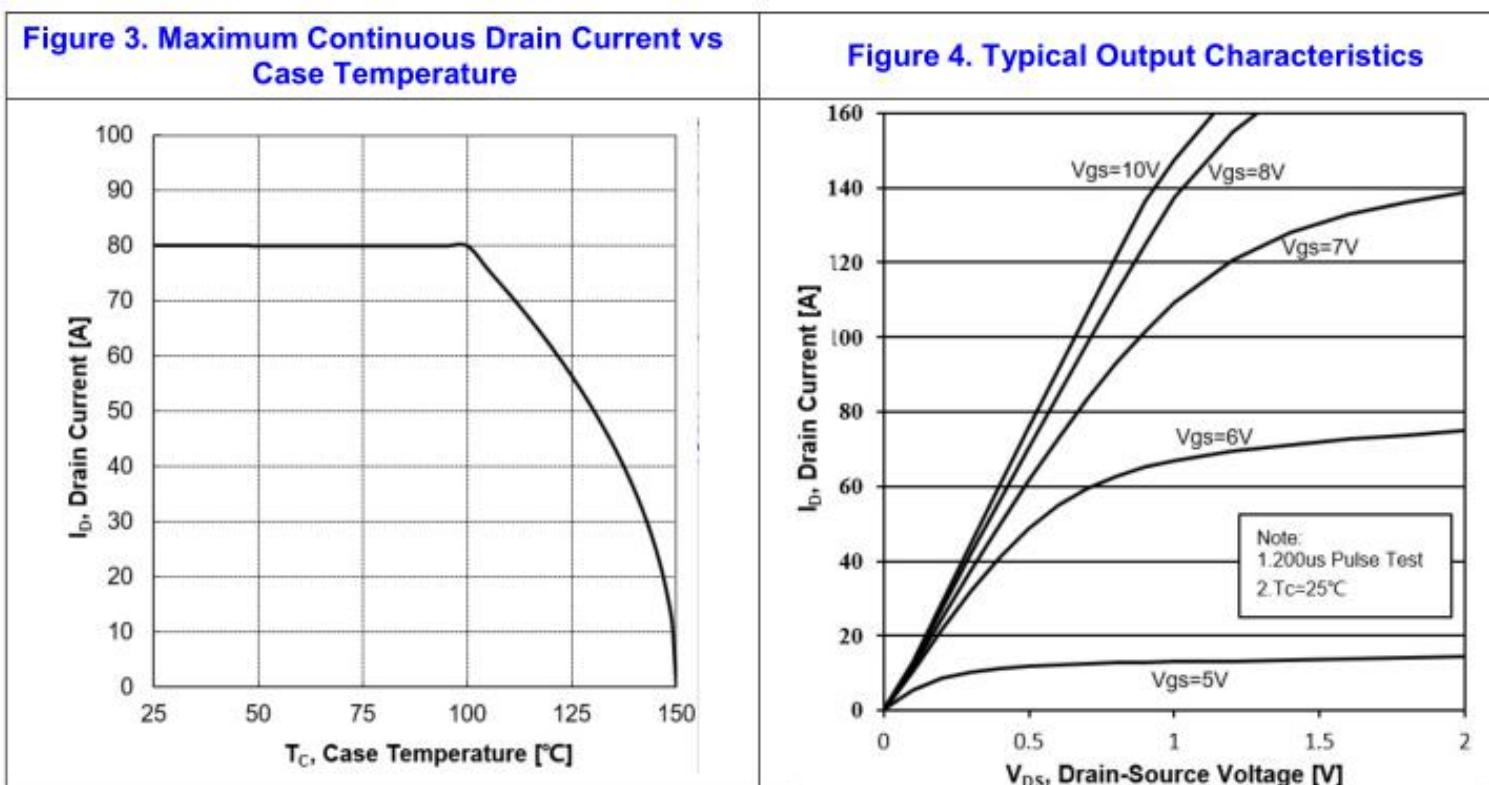
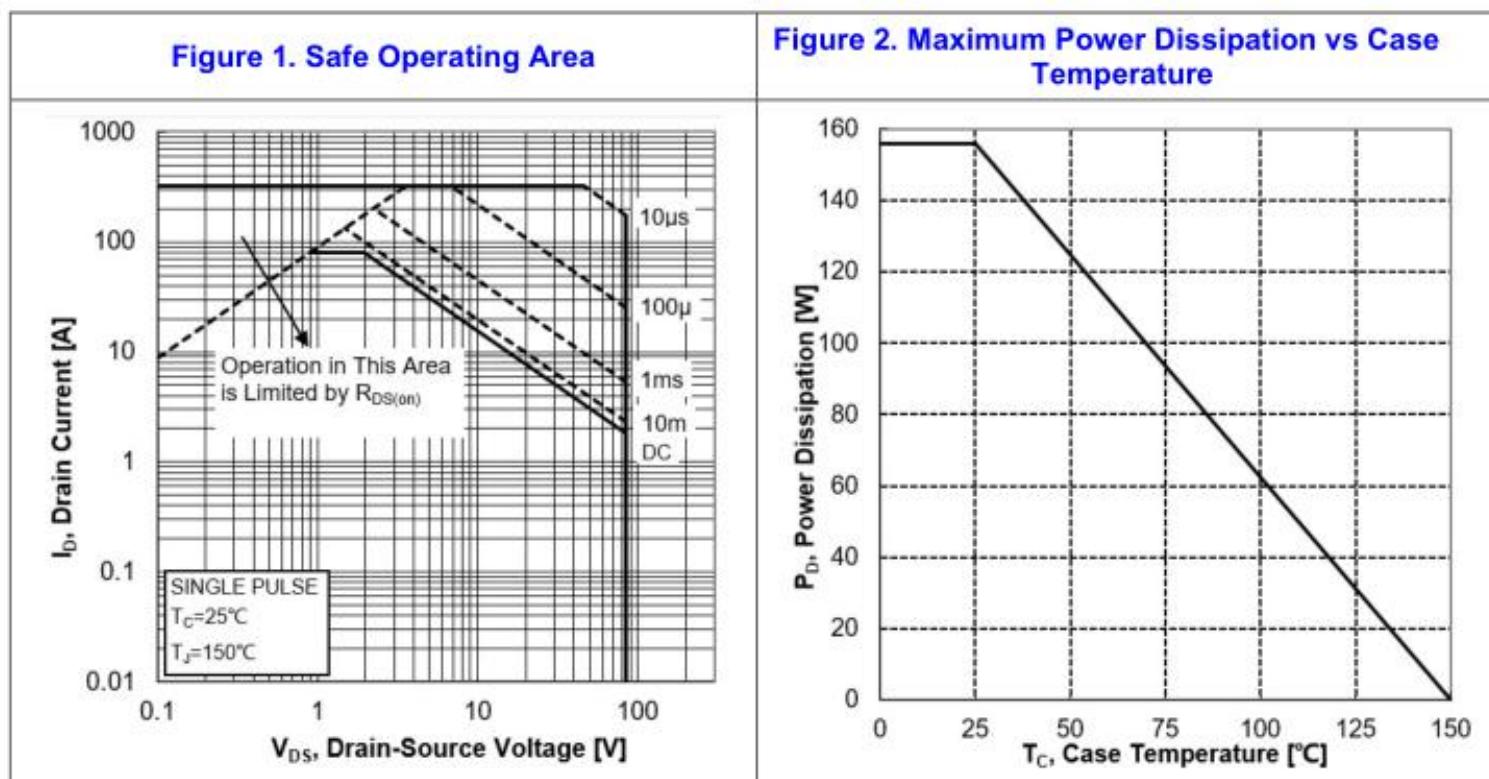


Figure 6. Typical Transfer Characteristics

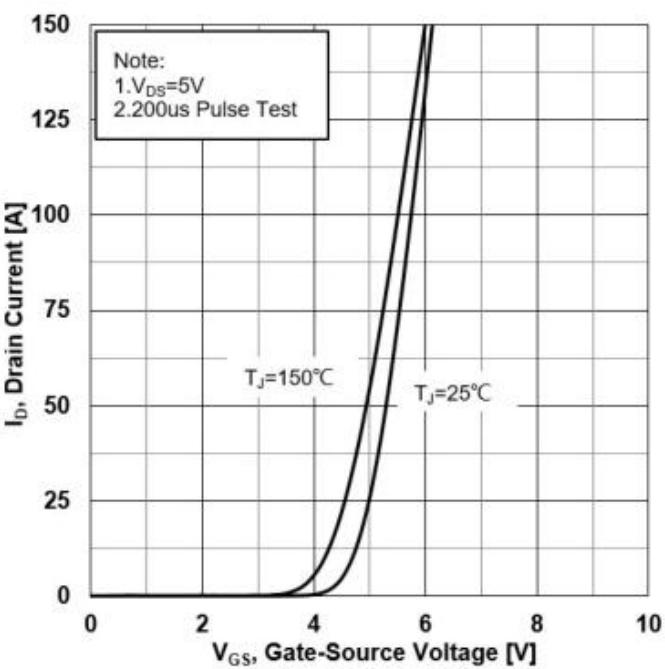


Figure 7. Source-Drain Diode Forward Characteristics

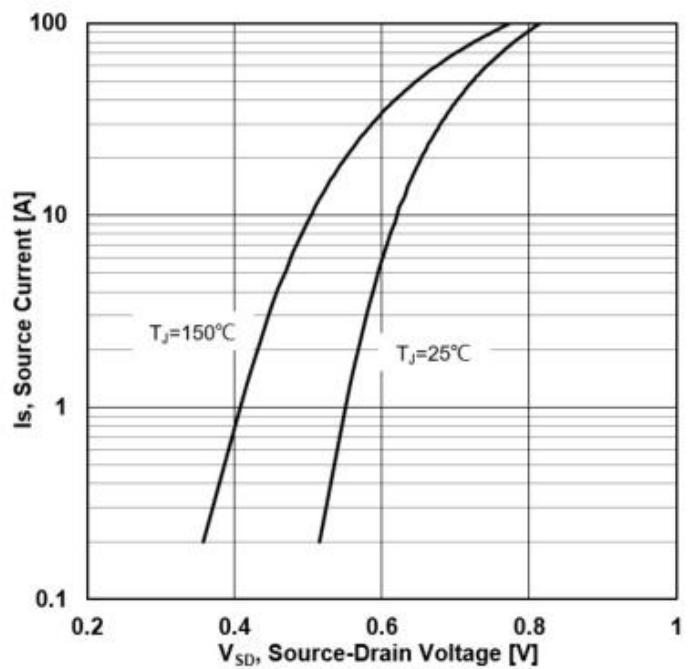


Figure 8. Drain-Source On-Resistance vs Drain Current

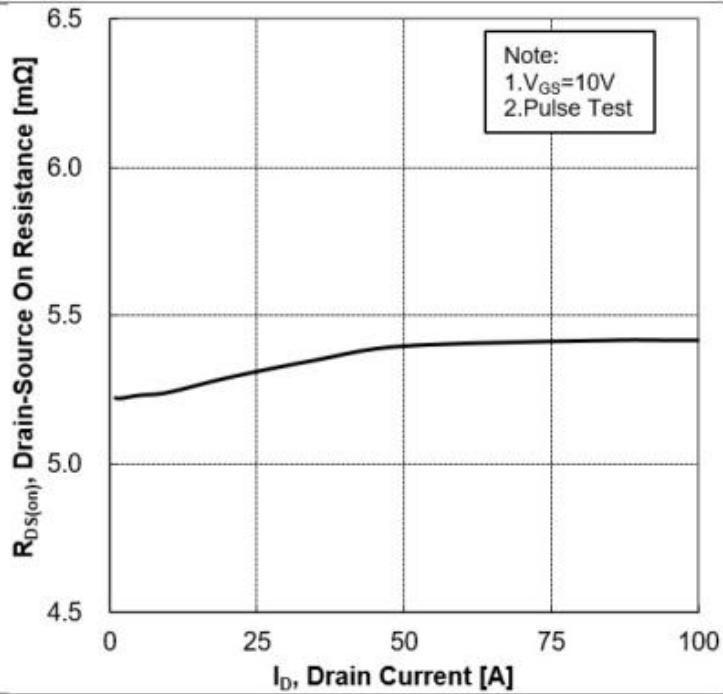


Figure 9. Normalized On-Resistance vs Junction Temperature

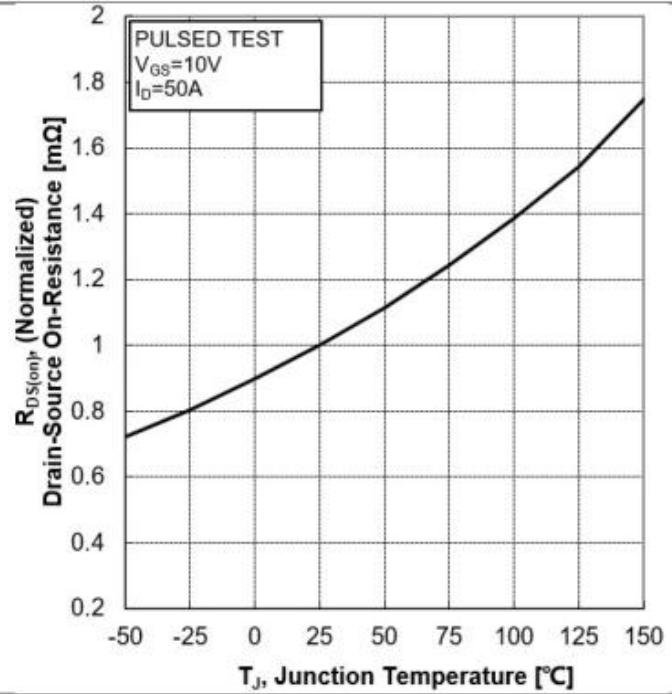


Figure 10. Normalized Threshold Voltage vs Junction Temperature

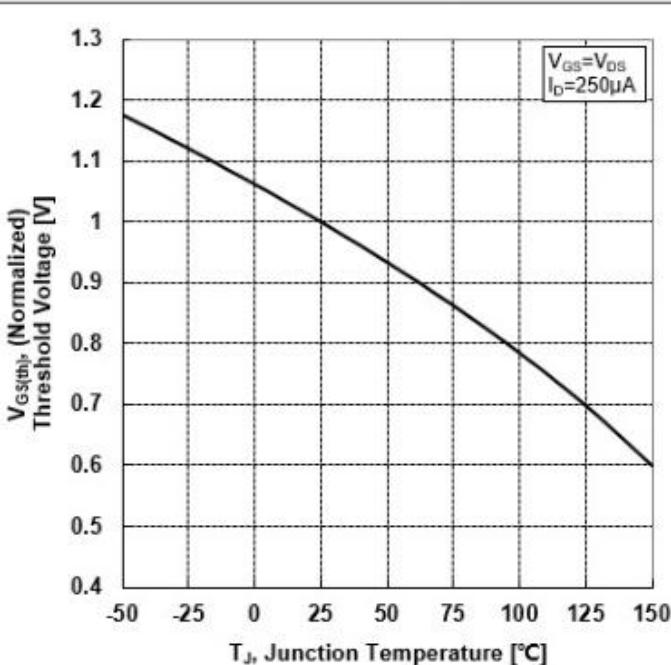


Figure 11. Normalized Breakdown Voltage vs Junction Temperature

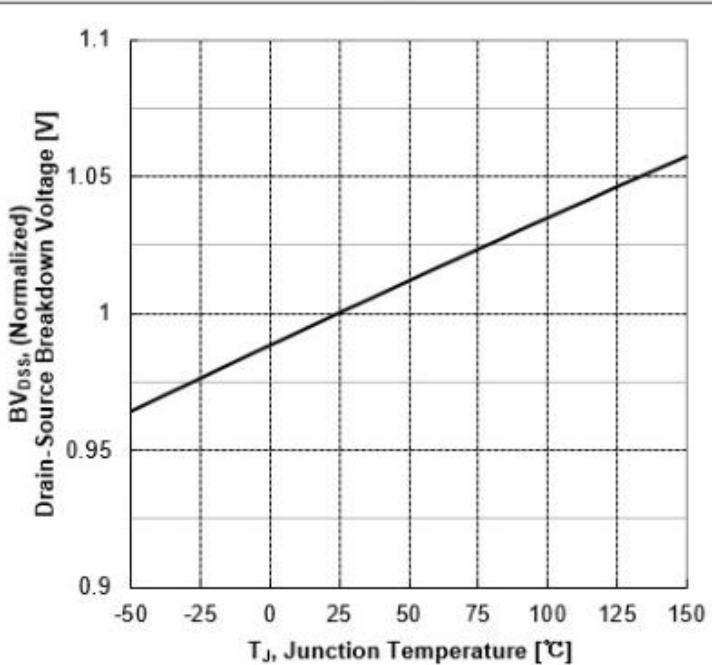


Figure 12. Capacitance Characteristics

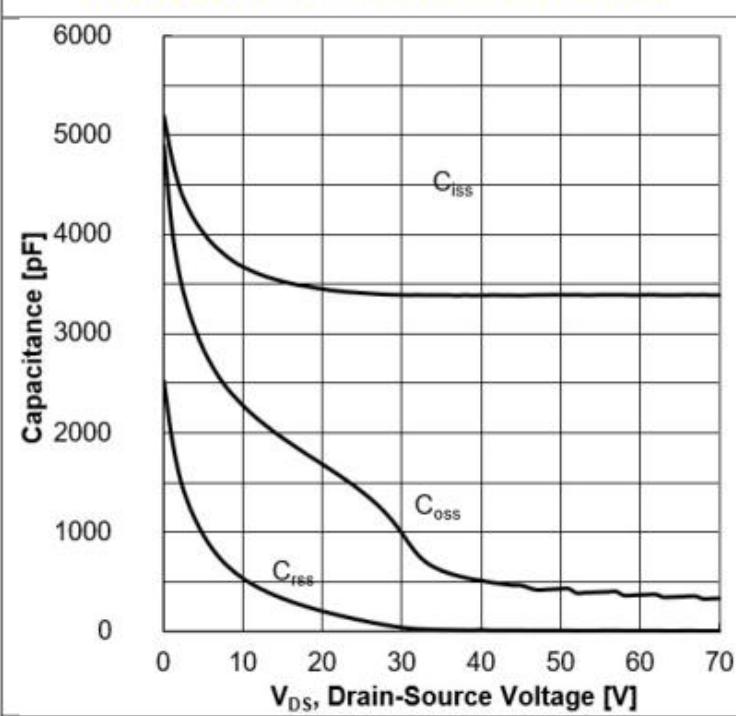
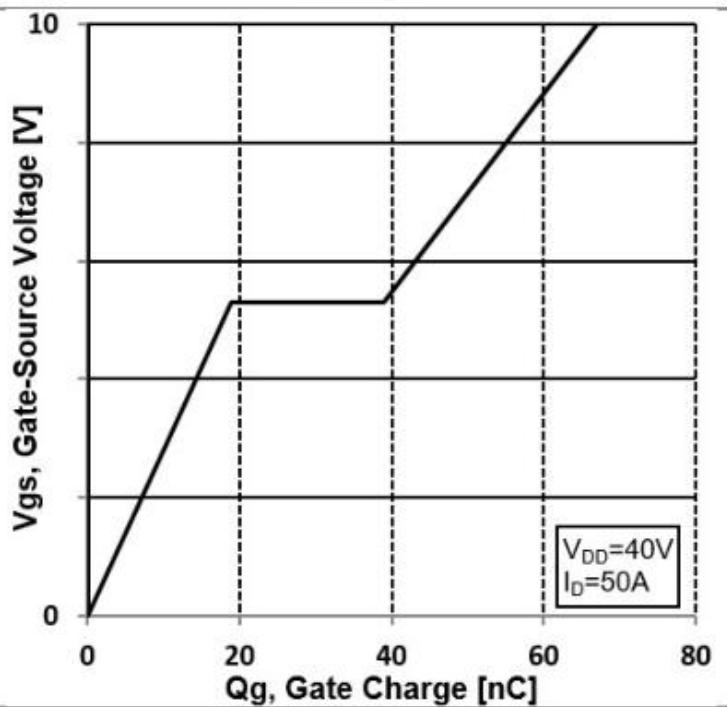


Figure 13. Typical Gate Charge vs Gate-Source Voltage



Test Circuit & Waveform

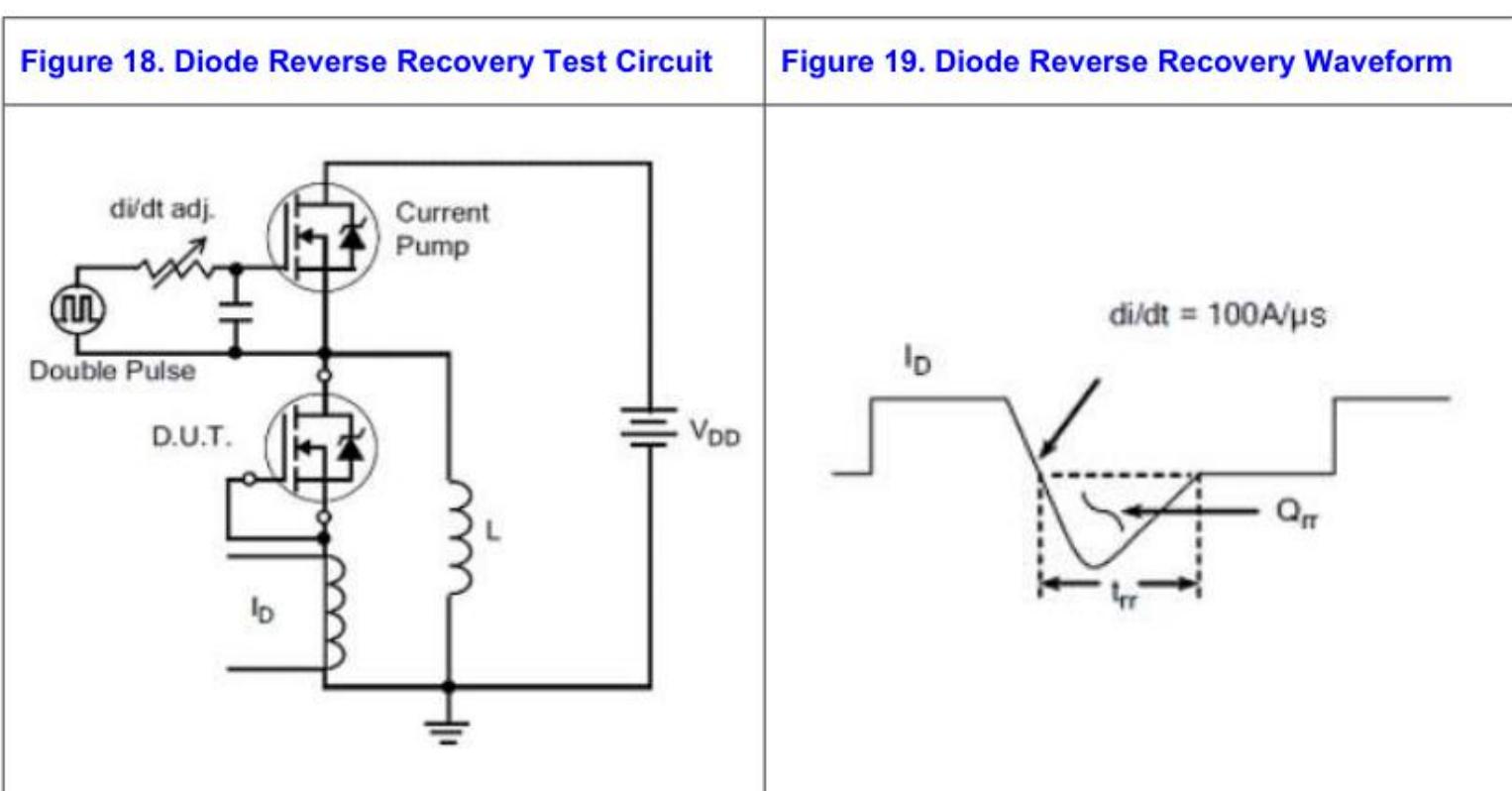
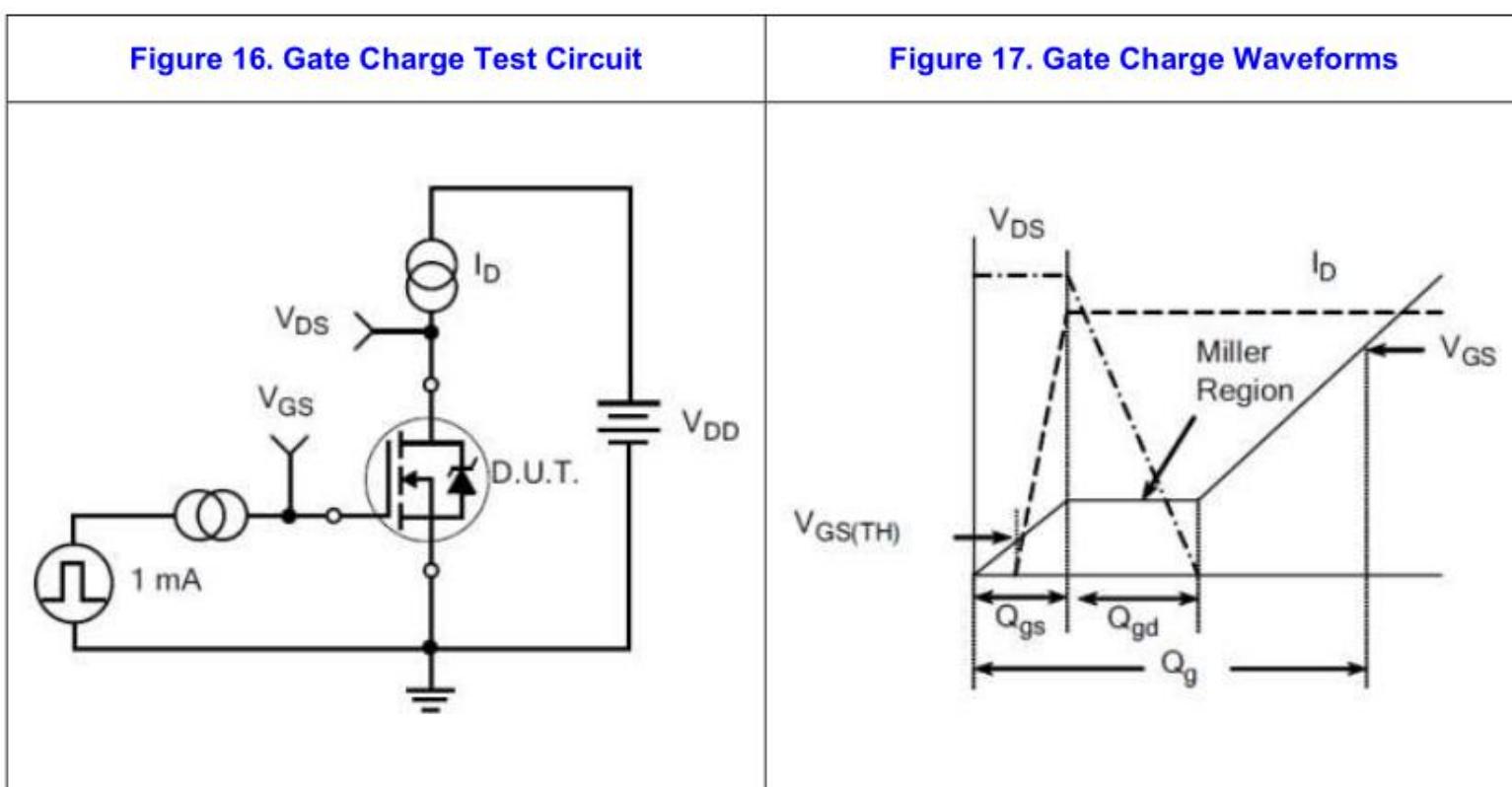
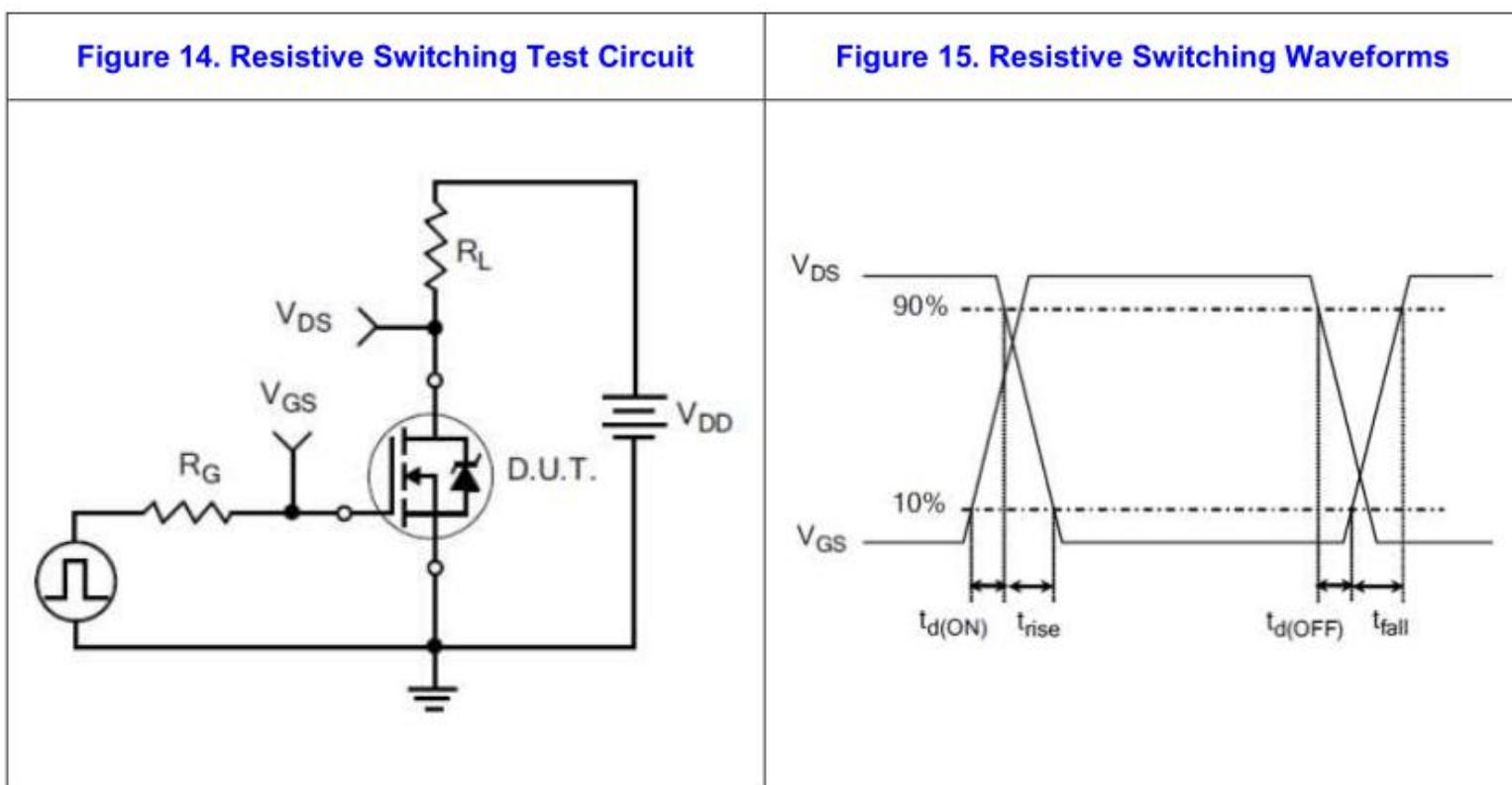


Figure 20. Unclamped Inductive Switching Test Circuit

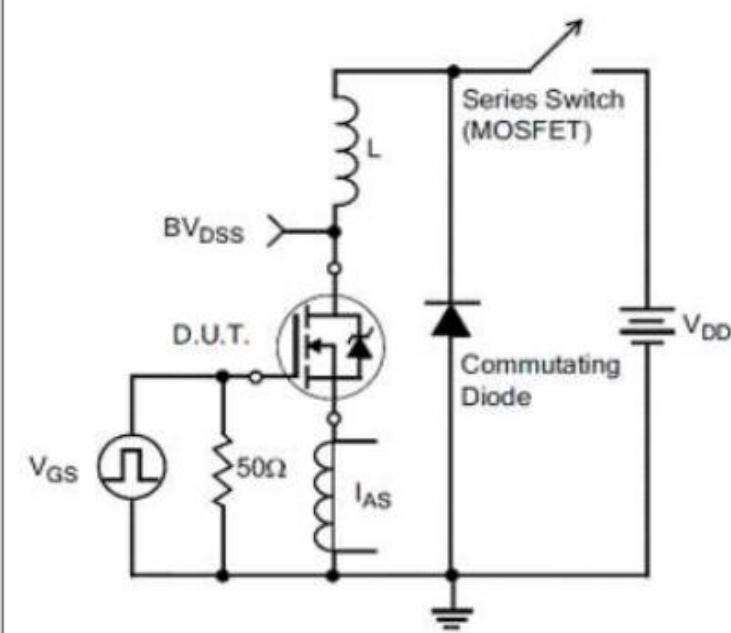
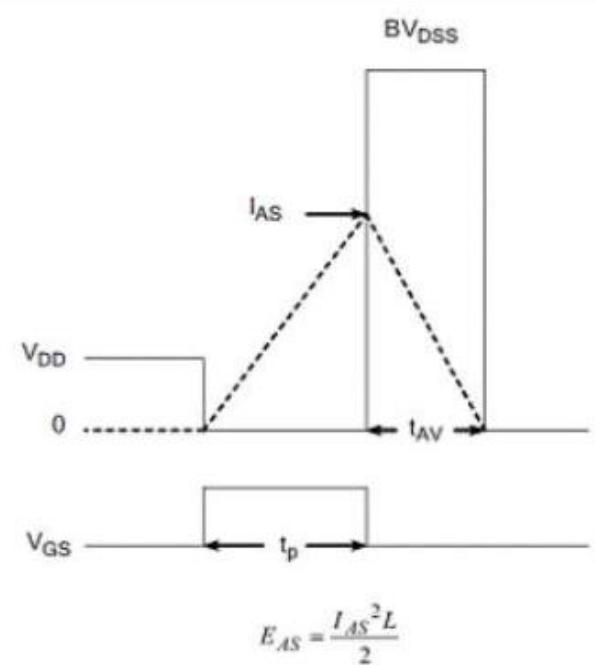
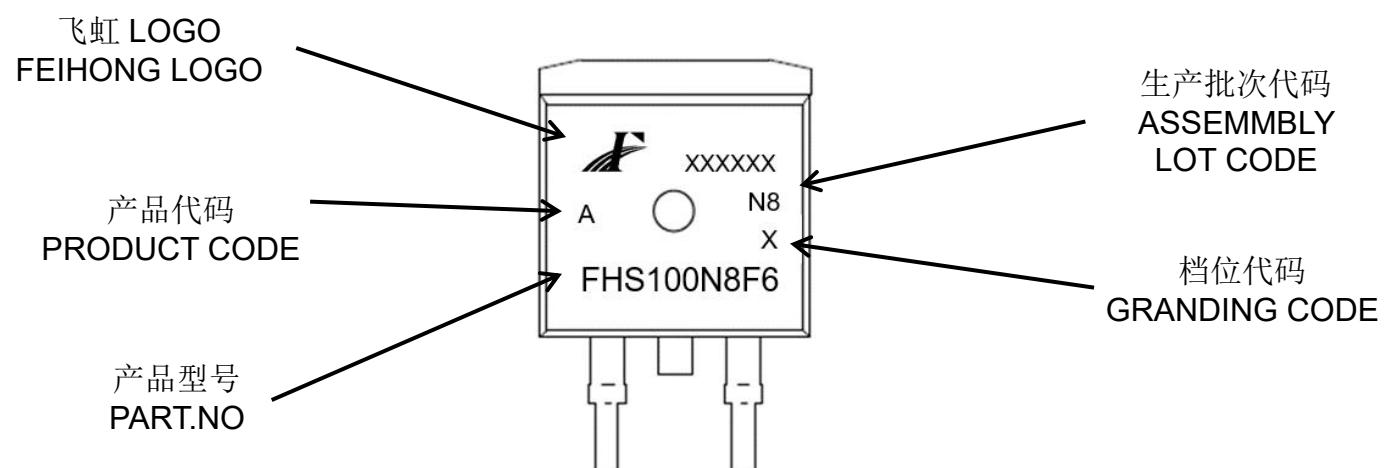
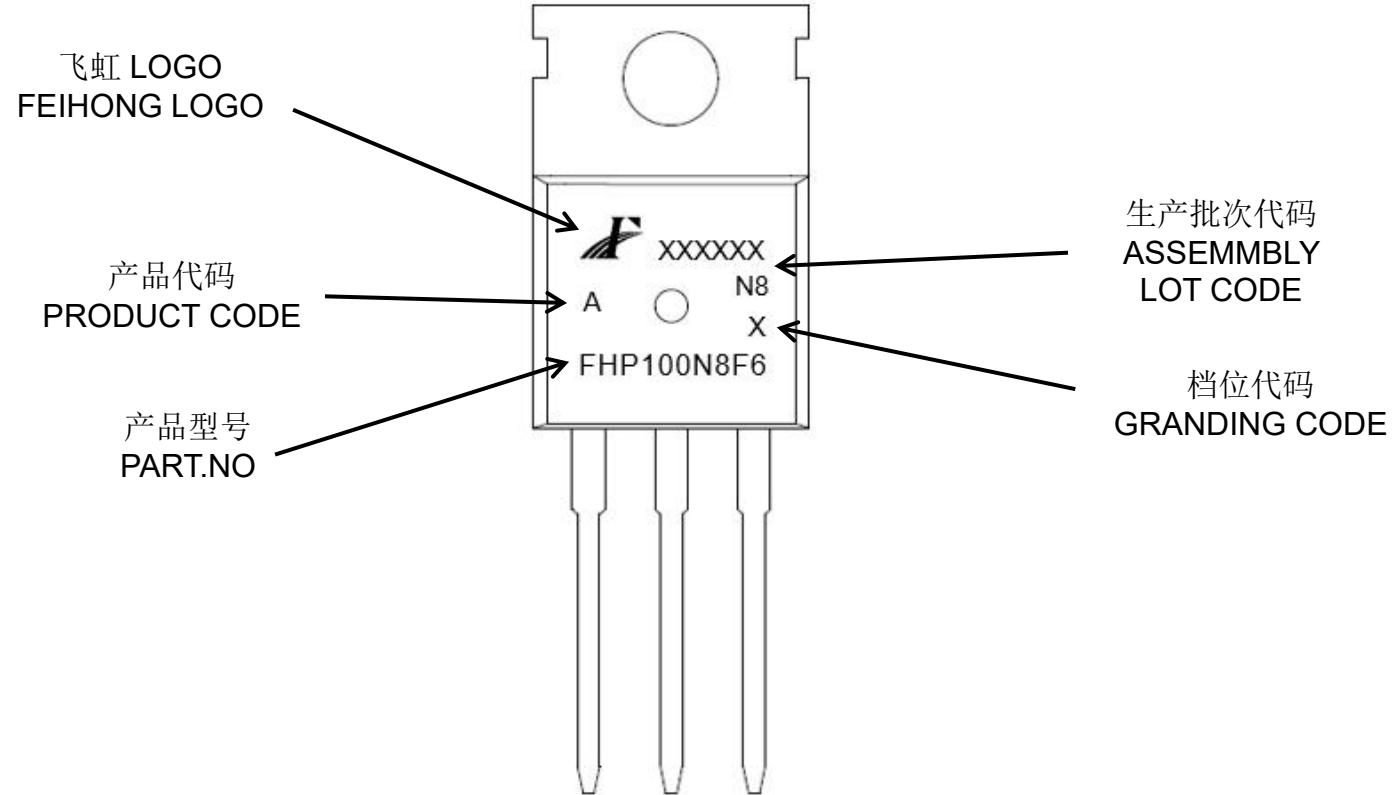


Figure 21. Unclamped Inductive Switching Waveform



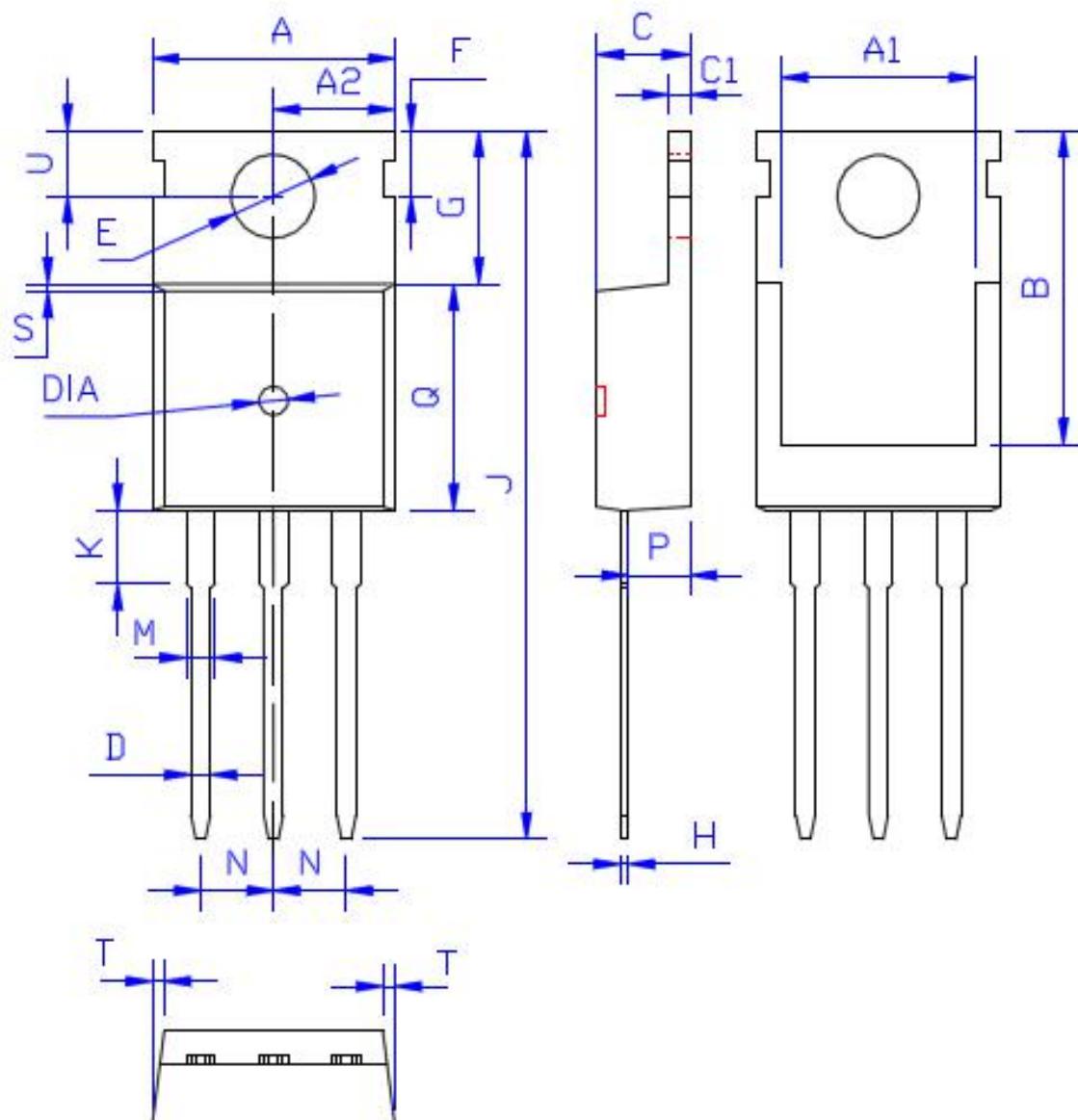
印记 Marking:



外形尺寸:

Package Dimension:

TO-220



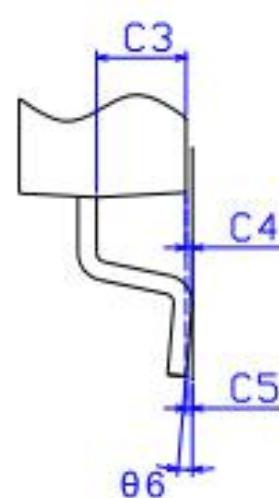
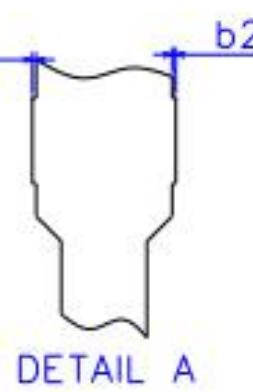
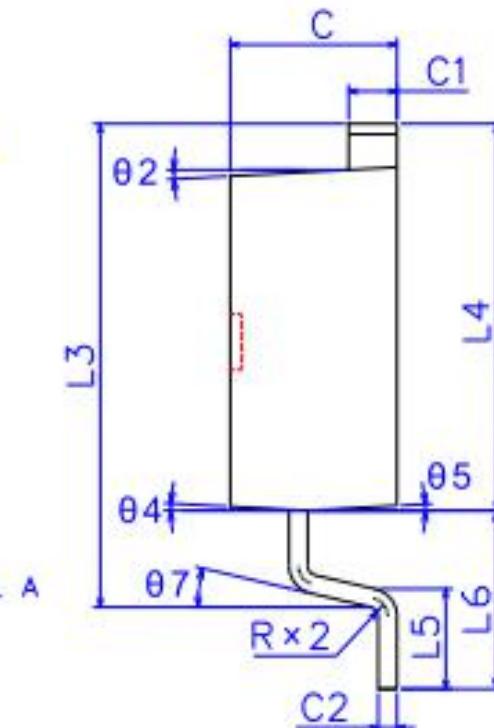
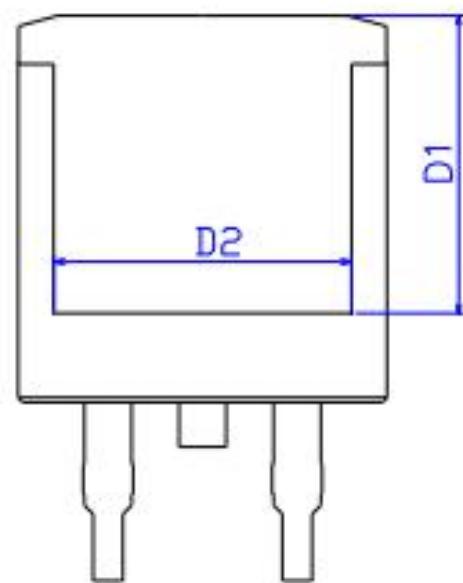
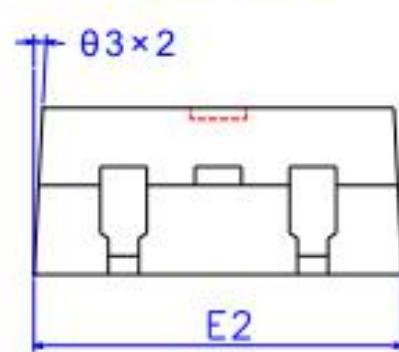
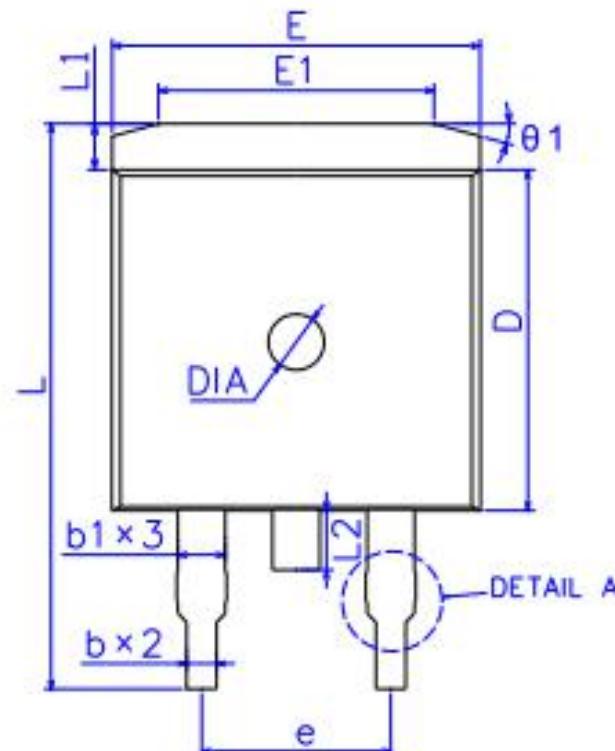
DIM	MILLIMETERS
A	10.00±0.30
A1	8.00±0.30
A2	5.00±0.30
B	13.20±0.40
C	4.50±0.20
C1	1.30±0.20
D	0.80±0.20
E	3.60±0.20
F	3.00±0.30
G	6.60±0.40
H	0.50±0.20
J	28.88±0.50
K	3.00±0.30
M	1.30±0.30
N	Typical 2.54
P	2.40±0.40
Q	9.20±0.40
S	0.25±0.15
T	0.25±0.15
U	2.80±0.30
DIA	宽 1.50±0.10 深 0.50 MAX

(Unit: mm)

外形尺寸:

Package Dimension:

TO-263



标注	尺寸(mm)
E	9.88 ± 0.10
E1	7.40 ± 0.20
E2	9.90 ± 0.15
L	15.20 ± 0.25
L1	1.30 ± 0.15
L2	1.60 ± 0.10
L3	13.00 ± 0.20
L4	10.40 ± 0.15
L5	2.60 ± 0.15
L6	4.80 ± 0.20
b	0.80 ± 0.07
b1	1.27 ± 0.07
b2	0.05 ± 0.07
C	4.48 ± 0.10
C1	1.30 ± 0.07
C2	0.50 ± 0.07
C3	2.40 ± 0.06
C4	0.10 ± 0.08
C5	0.10 ± 0.08
D	9.20 ± 0.10
D1	8.00 ± 0.10
D2	8.00 ± 0.10
R	0.50 ± 0.10
$\theta 1$	$15^\circ \pm 2^\circ$
$\theta 2$	$3^\circ \pm 2^\circ$
$\theta 3$	$3^\circ \pm 2^\circ$
$\theta 4$	$3^\circ \pm 2^\circ$
$\theta 5$	$3^\circ \pm 2^\circ$
$\theta 6$	$0^\circ \sim 6^\circ$
$\theta 7$	$13^\circ \pm 2^\circ$
e	5.08 ± 0.10
DIA	宽 1.50 ± 0.10 深 0.30 ± 0.15